## -ReNESAS

## 2SJ496

Silicon P Channel MOS FET
REJ03G0870-0300
(Previous: ADE-208-482A)
Rev.3.00
Sep 07, 2005

## Description

High speed power switching

## Features

- Low on-resistance
$\mathrm{R}_{\mathrm{DS}(\text { on })}=0.12 \Omega$ typ. $\left(\right.$ at $\left.\mathrm{V}_{\mathrm{GS}}=-10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=-2.5 \mathrm{~A}\right)$
- 4 V gate drive devices.
- Large current capacitance
$\mathrm{I}_{\mathrm{D}}=-5 \mathrm{~A}$


## Outline

RENESAS Package code: PRSS0003DC-A
(Package name: TO-92 Mod)


1. Source
2. Drain
3. Gate

## Absolute Maximum Ratings

$$
\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)
$$

| Item | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Drain to source voltage | $\mathrm{V}_{\mathrm{DSS}}$ | -60 | V |
| Gate to source voltage | $\mathrm{V}_{\mathrm{GSS}}$ | $\pm 20$ | V |
| Drain current | $\mathrm{I}_{\mathrm{D}}$ | -5 | A |
| Drain peak current | $\mathrm{I}_{\mathrm{D}(\text { pulse })}$ Note 1 | -20 | A |
| Body to drain diode reverse drain current | $\mathrm{I}_{\mathrm{DR}}$ | -5 | A |
| Avalanche current | $\mathrm{I}_{\mathrm{AP}}$ Note 3 | -5 | A |
| Avalanche energy | $\mathrm{E}_{\mathrm{AR}}{ }^{\text {Note } 3}$ | 2.14 | mJ |
| Channel dissipation | $\mathrm{Pch}^{\text {Note } 2}$ | 0.9 | W |
| Channel temperature | Tch | 150 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | Tstg | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |

Notes: 1. PW $\leq 100 \mu \mathrm{~s}$, duty cycle $\leq 10 \%$
2. Value at $\mathrm{Ta}=25^{\circ} \mathrm{C}$
3. Value at $\mathrm{Tch}=25^{\circ} \mathrm{C}, \mathrm{Rg} \geq 50 \Omega$

## Electrical Characteristics

$\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)$

| Item | Symbol | Min | Typ | Max | Unit | Test Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Drain to source breakdown voltage | $\mathrm{V}_{\text {(BR) } \mathrm{DSS}}$ | -60 | - | - | V | $\mathrm{I}_{\mathrm{D}}=-10 \mathrm{~mA}, \mathrm{~V}_{\mathrm{GS}}=0$ |
| Gate to source breakdown voltage | $\mathrm{V}_{\text {(BR) GSS }}$ | $\pm 20$ | - | - | V | $\mathrm{I}_{\mathrm{G}}= \pm 100 \mu \mathrm{~A}, \mathrm{~V}_{\mathrm{DS}}=0$ |
| Zero gate voltage drain current | Idss | - | - | -10 | $\mu \mathrm{A}$ | $\mathrm{V}_{\mathrm{DS}}=-60 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=0$ |
| Gate to source leak current | IGSS | - | - | $\pm 10$ | $\mu \mathrm{A}$ | $\mathrm{V}_{\mathrm{GS}}= \pm 16 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=0$ |
| Gate to source cutoff voltage | $\mathrm{V}_{\mathrm{GS}}$ (off) | -1.0 | - | -2.0 | V | $\mathrm{I}_{\mathrm{D}}=-1 \mathrm{~mA}, \mathrm{~V}_{\mathrm{DS}}=-5 \mathrm{~V}$ |
| Static drain to source on state resistance | $\mathrm{R}_{\mathrm{DS} \text { (on) }}$ | - | 0.12 | 0.16 | $\Omega$ | $\mathrm{I}_{\mathrm{D}}=-2.5 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=-10 \mathrm{~V}^{\text {Note } 4}$ |
|  | $\mathrm{R}_{\mathrm{DS} \text { (on) }}$ | - | 0.17 | 0.24 | $\Omega$ | $\mathrm{I}_{\mathrm{D}}=-2.5 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=-4 \mathrm{~V}^{\text {Note } 4}$ |
| Forward transfer admittance | \| $\mathrm{y}_{\text {ts }}$ \| | 3 | 5 | - | S | $\mathrm{I}_{\mathrm{D}}=-2.5 \mathrm{~A}, \mathrm{~V}_{\mathrm{DS}}=-10 \mathrm{~V}^{\text {Note } 4}$ |
| Input capacitance | Ciss | - | 600 | - | pF | $\begin{aligned} & V_{D S}=-10 \mathrm{~V} \\ & V_{G S}=0 \\ & f=1 \mathrm{MHz} \end{aligned}$ |
| Output capacitance | Coss | - | 290 | - | pF |  |
| Reverse transfer capacitance | Crss | - | 80 | - | pF |  |
| Turn-on delay time | $\mathrm{t}_{\mathrm{d} \text { (on) }}$ | - | 10 | - | ns | $\begin{aligned} & \mathrm{V}_{\mathrm{GS}}=-10 \mathrm{~V} \\ & \mathrm{I}_{\mathrm{D}}=-2.5 \mathrm{~A} \\ & \mathrm{R}_{\mathrm{L}}=12 \Omega \end{aligned}$ |
| Rise time | $\mathrm{tr}_{r}$ | - | 25 | - | ns |  |
| Turn-off delay time | $\mathrm{t}_{\mathrm{d} \text { (off) }}$ | - | 95 | - | ns |  |
| Fall time | $\mathrm{t}_{\mathrm{f}}$ | - | 55 | - | ns |  |
| Body to drain diode forward voltage | $\mathrm{V}_{\mathrm{DF}}$ | - | -1.0 | - | V | $\mathrm{I}_{\mathrm{F}}=-5 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=0$ |
| Body to drain diode reverse recovery time | $\mathrm{trr}_{\text {r }}$ | - | 65 | - | ns | $\begin{aligned} & \mathrm{I}_{\mathrm{F}}=-5 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=0 \\ & \mathrm{di}_{\mathrm{F}} / \mathrm{dt}=50 \mathrm{~A} / \mu \mathrm{s} \end{aligned}$ |

Note: 4. Pulse test

## Main Characteristics



Static Drain to Source on State Resistance vs. Temperature


Body-Drain Diode Reverse
Recovery Time


Reverse Drain Current $I_{D R}$ (A)

Dynamic Input Characteristics


Forward Transfer Admittance vs. Drain Current


Typical Capacitance vs. Drain to Source Voltage


Drain to Source Voltage $\mathrm{V}_{\mathrm{DS}}(\mathrm{V})$

Switching Characteristics




## Package Dimensions



## Ordering Information

| Part Name | Quantity |  |
| :--- | :--- | :--- |
| 2SJ496TZ-E | 2500 pcs | Taping |

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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